

## Soldered SAM data sheet SAM- $\lambda$ -A- $\tau$ -4.0-25.4s-c or SAM- $\lambda$ -A- $\tau$ -4.0-25.4s-e

SAM chip area standard: 4.0 mm x 4.0 mm

optional: other dimensions on request

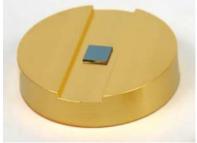
Chip thickness standard: 450 µm

Front side protection The SAM is protected with a dielectric front layer.

The SAM chip is soldered on a gold plated Cu-cylinder with  $\emptyset$  25.4 mm. The solder provides a low thermal resistance between the SAM and the mount.

- The **standard** position of the SAM is in the center of the mount  $\rightarrow$  x = 4.0-25.4s-c.
- Optional the SAM can be soldered at the edge of the mount without extra charges
  → x = 4.0-25.4s-e.

Center mounted SAM



Edge mounted SAM



## Dimensions:

